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PATENT TRADEMARK OFFICE

Patent
Case No.: 53434US009

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: HOGERTON, PETER B.

Application No.: 09/690,600 Group Art Unit: 2827

Filed: October 17, 2000 Examiner: Luan C. Thai

Title: SOLVENT ASSISTED BURNISHING OF PRE-UNDERFILLED SOLDER-BUMPED WAFERS FOR FLIPCHIP BONDING

REQUEST FOR EXTENSION OF TIME UNDER 37 CFR § 1.136(A)Commissioner for Patents
Washington, DC 20231

CERTIFICATE OF TRANSMISSION

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Dean M. Harts

Dear Sir:

This is a request for an extension of time under the provisions of 37 CFR § 1.136(a).

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- 37 CFR § 1.17(a)(1) - Extension within first month
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Respectfully submitted,

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